Features

- High Power SPDT Switch and 2-Stage LNA
- Broadband: 1 - 6 GHz
- No External Matching Components Required
- RX Mode Gain:
  35.0 dB @ 2.50 GHz
  34.5 dB @ 3.75 GHz
  33.5 dB @ 4.50 GHz
- RX Mode Noise Figure:
  1.2 dB @ 2.50 GHz
  1.3 dB @ 3.75 GHz
  1.5 dB @ 4.50 GHz
- TX Mode at 2.3 - 5.0 GHz:
  Insertion Loss: 0.4 dB
  P0.1dB: 40.5 dBm
- Single 5 V Bias
- Low DC Current: 78 mA in RX Mode
- Integrated Control Circuitry with 1.8 V Logic
- Lead-Free 6 mm 20 Lead QFN Package
- HBM ESD Class 1C
- RoHS* Compliant

Description

The MAMF-011119 is a compact surface mount, highly integrated high power SPDT switch and 2-stage low noise amplifier (LNA) module. It includes an antenna switch and a LNA in a compact 6 mm QFN package. All the bias circuitry and matching components are internal to the module.

This module operates from 1 - 6 GHz and features high power handling, low noise figure, high linearity and low power consumption. The module requires a single 5 V supply and the T/R switch is 1.8 V CMOS compatible.

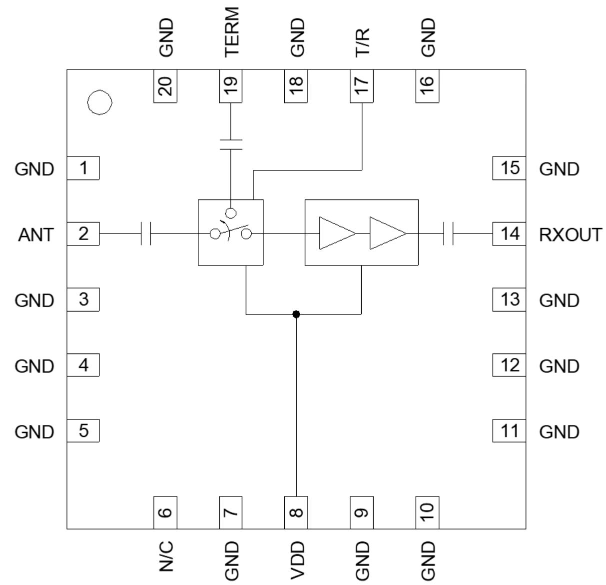
The MAMF-011119 is ideally suited for 5G Massive MIMO, Small Cell BTS, or other TDD-based communication systems.

Ordering Information[1,2]

Part #	Package
MAMF-011119-TR1000	1000 piece reel
MAMF-011119-TR3000	3000 piece reel
MAMF-011119-001SMB	Sample Board

1. Reference Application Note M513 for reel size information.
2. All sample boards include 5 loose parts.

Functional Schematic



Pin Configuration[3]

Pin #	Pin Name	Description
1, 3-5, 7, 9-13, 15, 16, 18, 20	GND	Ground
2	ANT	RF Antenna Port
6	N/C	Internally No Connect
8	V_{DD}	Supply Voltage
14	RXOUT	RX Output Port
17	T/R	Logic Signaling Pin
19	TERM	Termination Port
21	Paddle[4]	Ground

3. MACOM recommends connecting GND and No Connection (N/C) pins to ground.
4. The exposed paddle centered on the package bottom must be connected to RF, DC & thermal ground.

* Restrictions on Hazardous Substances, compliant to current RoHS EU directive.

AC Electrical Specifications (RX Mode)
P_{IN} = -30 dBm, T_C = +25°C, V_{DD} = 5 V, Z_0 = 50 Ω

Parameter	Test Conditions	Units	Min.	Typ.	Max.
Gain	ANT to RXOUT, 2.5 GHz ANT to RXOUT, 3.75 GHz	dB	32	35.0 34.5	37
Input IP3	P_{IN}/tone = -33 dBm, Tone Delta = 2 MHz, ANT to RXOUT, 2.5 GHz ANT to RXOUT, 3.75 GHz	dBm	—	-6 -4	—
Input P1dB	ANT to RXOUT, 2.5 GHz ANT to RXOUT, 3.75 GHz	dBm	-20	-18 -17	—
Noise Figure	ANT to RXOUT, 2.5 GHz ANT to RXOUT, 3.75 GHz	dB	—	1.2 1.3	—
ANT Port Return Loss	ANT Port, 2.5 GHz ANT Port, 3.75 GHz	dB	—	17 21	—
RXOUT Port Return Loss	RXOUT Port, 2.5 GHz RXOUT Port, 3.75 GHz	dB	—	21 24	—
Reverse Isolation	RXOUT to ANT, 2.5 GHz RXOUT to ANT, 3.75 GHz	dB	—	51 50	—

AC Electrical Specifications (TX Mode)
P_{IN} = -30 dBm, T_C = +25°C, V_{DD} = 5 V, Z_0 = 50 Ω (unless otherwise indicated)

Parameter	Test Conditions	Units	Min.	Typ.	Max.
Insertion Loss	ANT to TERM, 2.5 GHz ANT to TERM, 3.75 GHz	dB	—	0.4 0.4	1.0
P0.1dB Compression Point	ANT to TERM, 2.5 GHz ANT to TERM, 3.75 GHz	dBm	—	40.5 40.5	—
ANT Port Return Loss	ANT Port, 2.5 GHz ANT Port, 3.75 GHz	dB	—	22 25	—
TERM Port Return Loss	TERM Port, 2.5 GHz TERM Port, 3.75 GHz	dB	—	21 25	—
ANT Port Input Power	ANT Port, 2.5 GHz, CW, T_C = 105°C ANT Port, 2.5 GHz, LTE (8dB PAR), T_C = 105°C	dBm	—	39 37	—

Transient Electrical Specifications

Freq. = 2.5 GHz, P_{IN} = -30 dBm, T_C = 25°C, V_{DD} = 5 V, Z_0 = 50 Ω

Parameter	Test Conditions	Units	Min.	Typ.	Max.
T/R Gain Settling Time	ANT to RXOUT gain settling time within 0.3 dB of final value after T/R command	µs	—	0.3	—
T/R Insertion Loss Settling Time	ANT to TERM path insertion loss settling time within 0.3 dB of final value after T/R command	µs	—	0.3	—
Power on Gain Settling Time	ANT to RXOUT gain settling time within 0.5 dB of final value after DC power on	ms	—	1	—
Power on Insertion Loss Settling Time	ANT to TERM settling time within 0.5 dB of final value after DC power on	ms	—	1	—

DC Electrical Specifications

T_C = 25°C, V_{DD} = 5 V, Z_0 = 50 Ω

Parameter	Test Conditions	Units	Min.	Typ.	Max.
Supply Voltage	—	V	4.75	5	5.25
Supply Current	RX Mode TX Mode	mA	—	78 1.4	—
T/R Control Voltage	RX Mode, Logic High TX Mode, Logic Low	V	1.073 -0.3	—	2.5 0.683
T/R Logic Input Current	RX Mode, Logic High TX Mode, Logic Low	µA	—	40 -2	—

Control Truth Table

T/R Control	
RX Mode	Logic High
TX Mode	Logic Low or Open

Absolute Maximum Ratings[5,6]

Parameter	Absolute Maximum
Antenna Input Power[7] Freq. = 2.5 GHz: RX Mode TX Mode	 23 dBm LTE (8 dB PAR), 26 dBm CW 39 dBm LTE (8 dB PAR), 42 dBm CW
DC Voltages: V_{DD}, ANT & TERM T/R & RXOUT	 -0.5 to +5.5 V -0.5 to +2.75 V
Junction Temperature: RX Mode[8,10] TX Mode[8,10] TX Mode[7]	 +150°C +125°C +140°C
Operating Temperature[9]	-40°C to +105°C
Storage Temperature	-55°C to +150°C

5. Exceeding any one or combination of these limits may cause permanent damage to this device.
6. MACOM does not recommend sustained operation near these survivability limits.
7. Single event, up to 10 seconds duration.
8. Operating at nominal conditions with $T_J \leq +150°C$ (RX Mode) and $T_J \leq +125°C$ (TX Mode) will ensure MTTF >> 1×10^6 hours.
9. Operating/Case temperature (T_C) is the temperature of the exposed paddle.
10. Junction Temperature (T_J) = $T_C + \Theta_{JC} * P_{DISS}$ where P_{DISS} is the total DC & RF dissipated power.
    - RX Mode: Typical thermal resistance (Θ_{JC}) = 33.4ºC/W.
    - TX Mode: Typical thermal resistance (Θ_{JC}) = 9.8ºC/W.

Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.

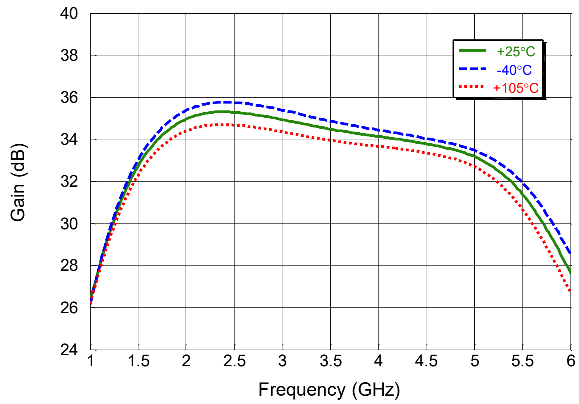
Parameter	Rating	Standard
Human Body Model (HBM)	1000 V (Class 1C)	ESDA/JEDEC JS -001
Charged Device Model (CDM)	1000 V (Class C3)	ESDA/JEDEC JS -002

Power Supplies

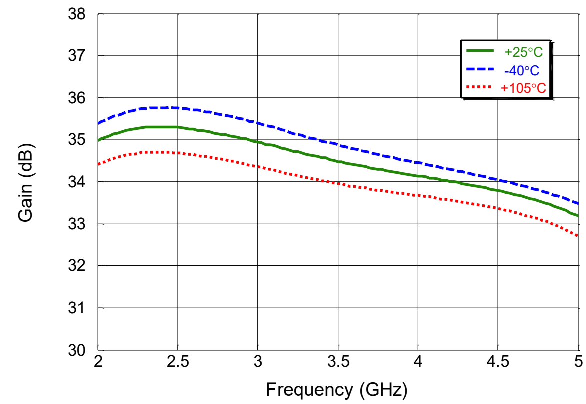
De-coupling capacitors should be placed at the V_{DD} supply pin to minimize noise and fast transients. Supply voltage change or transients should have a slew rate smaller than 1 V / 10 µs. In addition, all control pins should remain at 0 V (+/- 0.3 V) and no RF power should be applied while the supply voltage ramps or while it returns to zero.

Typical Performance Curves
P_{IN} = -30 dBm, V_{DD} = 5 V, Z_0 = 50 Ω (unless otherwise indicated)

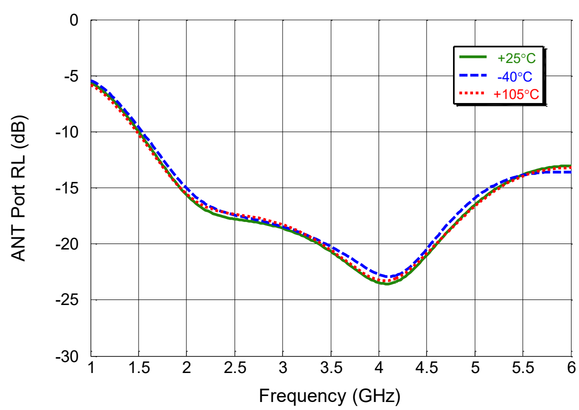
ANT to RXOUT Gain[11] - RX Mode



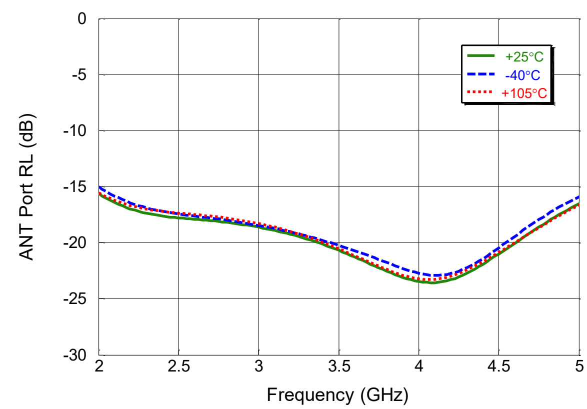
ANT to RXOUT Gain[11] - RX Mode



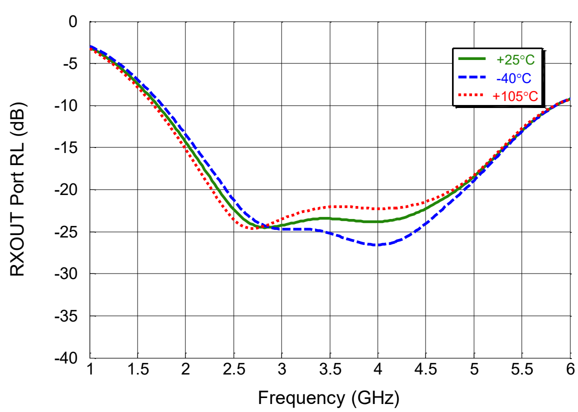
ANT Port Return Loss - RX Mode



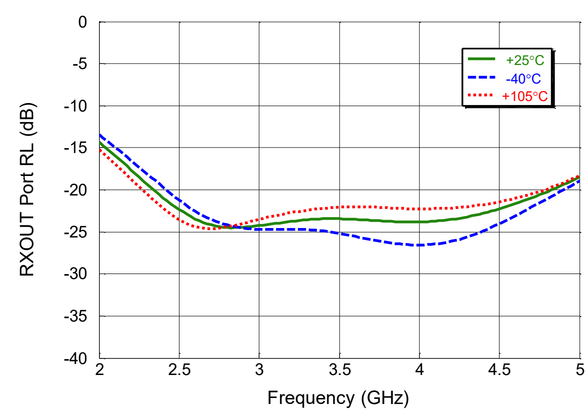
ANT Port Return Loss - RX Mode



RXOUT Port Return Loss - RX Mode



RXOUT Port Return Loss - RX Mode

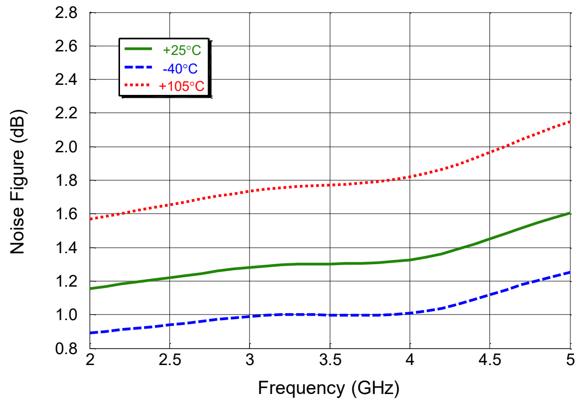


11. For gain, noise figure, insertion loss and isolation plots, RF trace and connector losses are de-embedded.

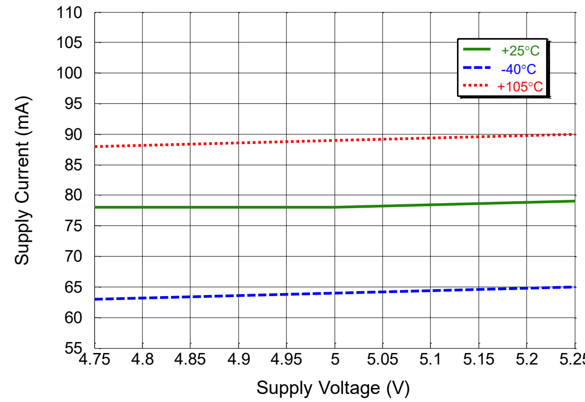
Typical Performance Curves

P_{IN} = -30 dBm, V_{DD} = 5 V, Z_0 = 50 Ω (unless otherwise indicated)

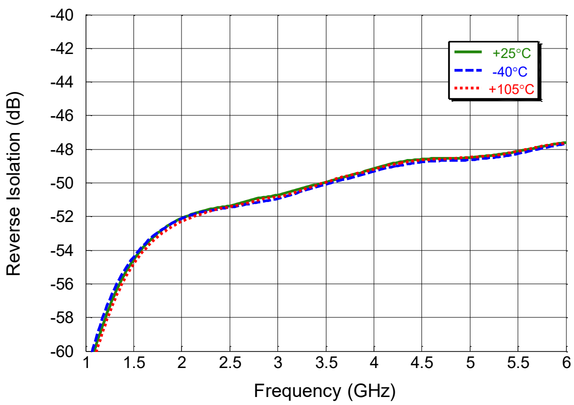
ANT to RXOUT Noise Figure[11] - RX Mode



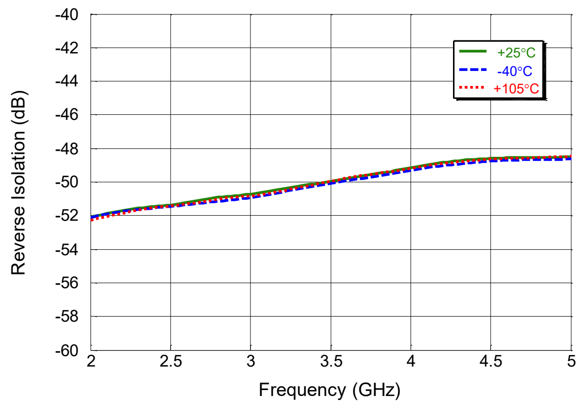
Supply Current - RX Mode



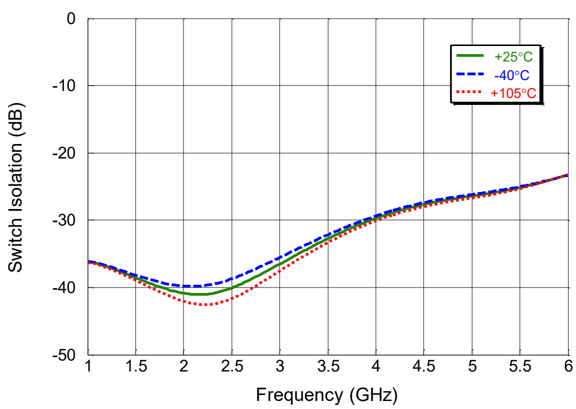
ANT to RXOUT Port Reverse Isolation[11] - RX Mode



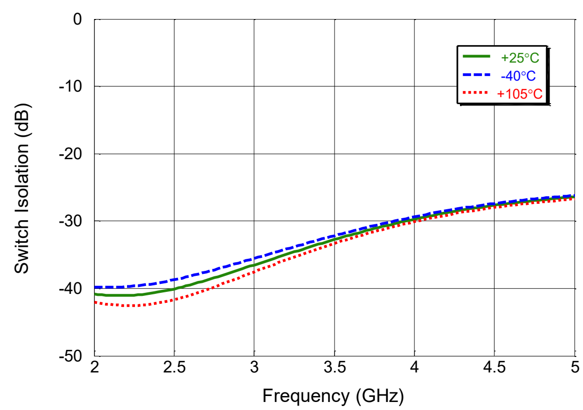
ANT to RXOUT Port Reverse Isolation[11] - RX Mode



ANT to TERM Port Switch Isolation[11] - RX Mode



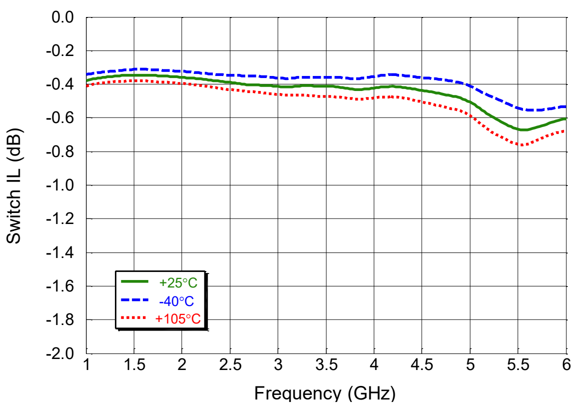
ANT to TERM Port Switch Isolation[11] - RX Mode



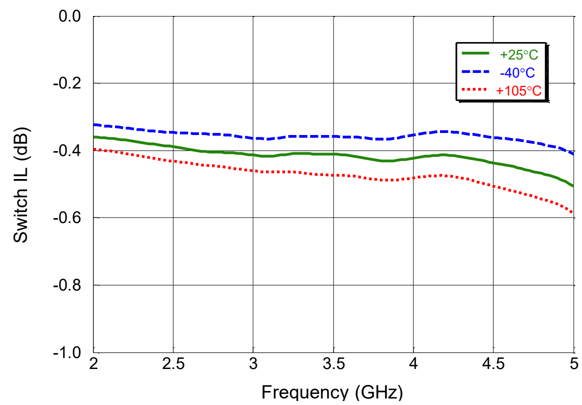
11. For gain, noise figure, insertion loss and isolation plots, RF trace and connector losses are de-embedded.

Typical Performance Curves
P_{IN} = -30 dBm, V_{DD} = 5 V, Z_0 = 50 Ω (unless otherwise indicated)

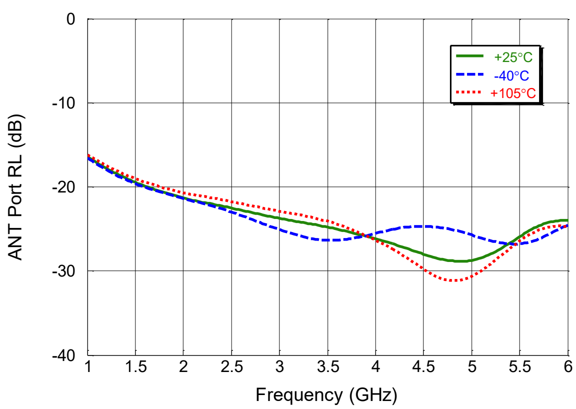
ANT to TERM Switch Insertion Loss[11] - TX Mode



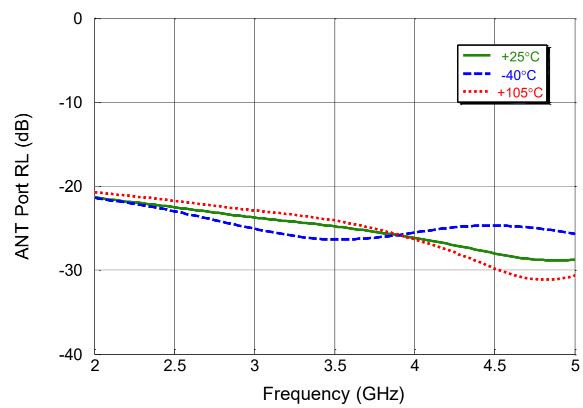
ANT to TERM Switch Insertion Loss[11] - TX Mode



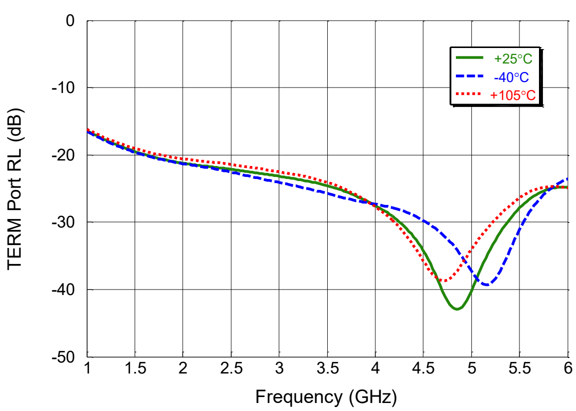
ANT Port Return Loss - TX Mode



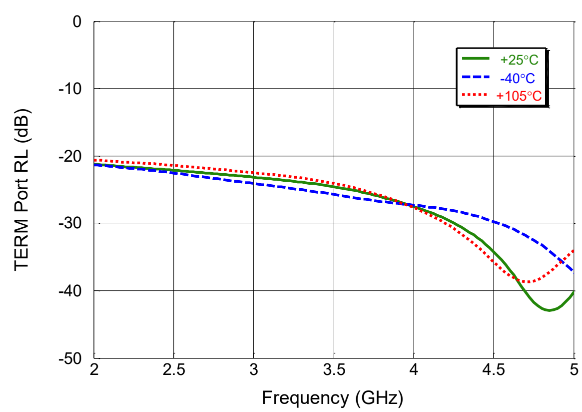
ANT Port Return Loss - TX Mode



TERM Port Return Loss - TX Mode



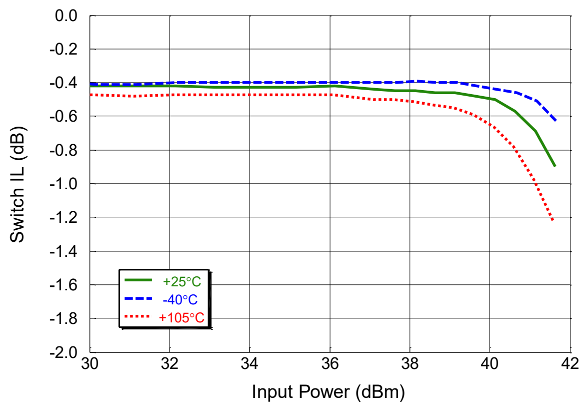
TERM Port Return Loss - TX Mode



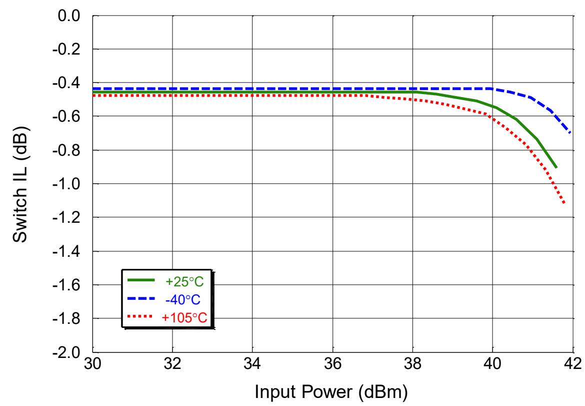
11. For gain, noise figure, insertion loss and isolation plots, RF trace and connector losses are de-embedded.

Typical Performance Curves
P_{IN} = -30 dBm, V_{DD} = 5 V, Z_0 = 50 Ω (unless otherwise indicated)

ANT to TERM Port Compression Characteristic[11] at 2.5 GHz - TX mode

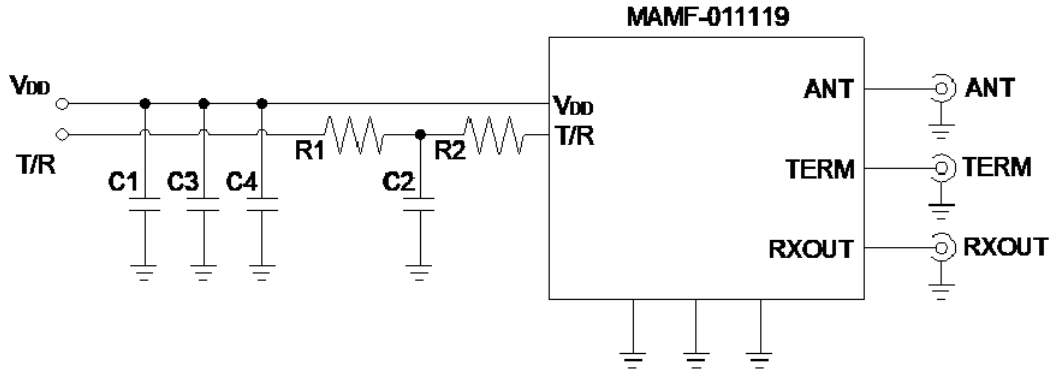


ANT to TERM Port Compression Characteristic[11] at 3.75 GHz - TX mode

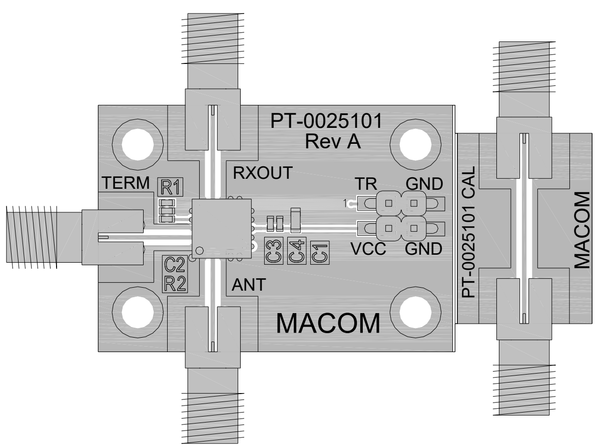


11. For gain, noise figure, insertion loss and isolation plots, RF trace and connector losses are de-embedded.

Sample Board Schematic



Sample Board PCB Layout

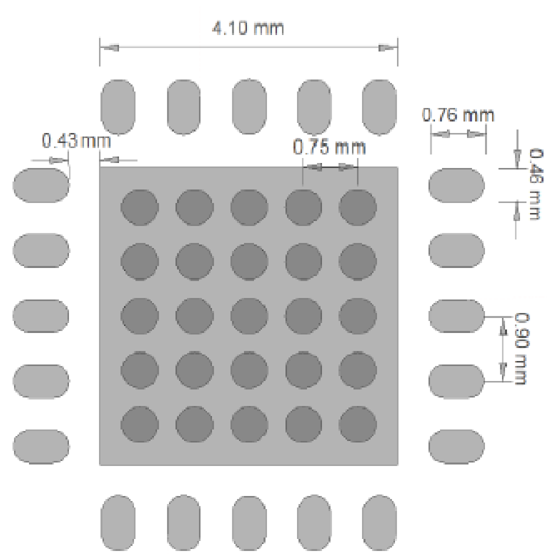


- Material: Megtron 4S R-5735S
- Dielectric thickness: 0.254 mm
- Track/Gap: 0.45/0.6 mm
- Finished copper thickness: 44 µm +/- 10 µm
- Finish both sides: 0.075 µm gold over 4.5 µm nickel
- Further layout information available on request

Parts List

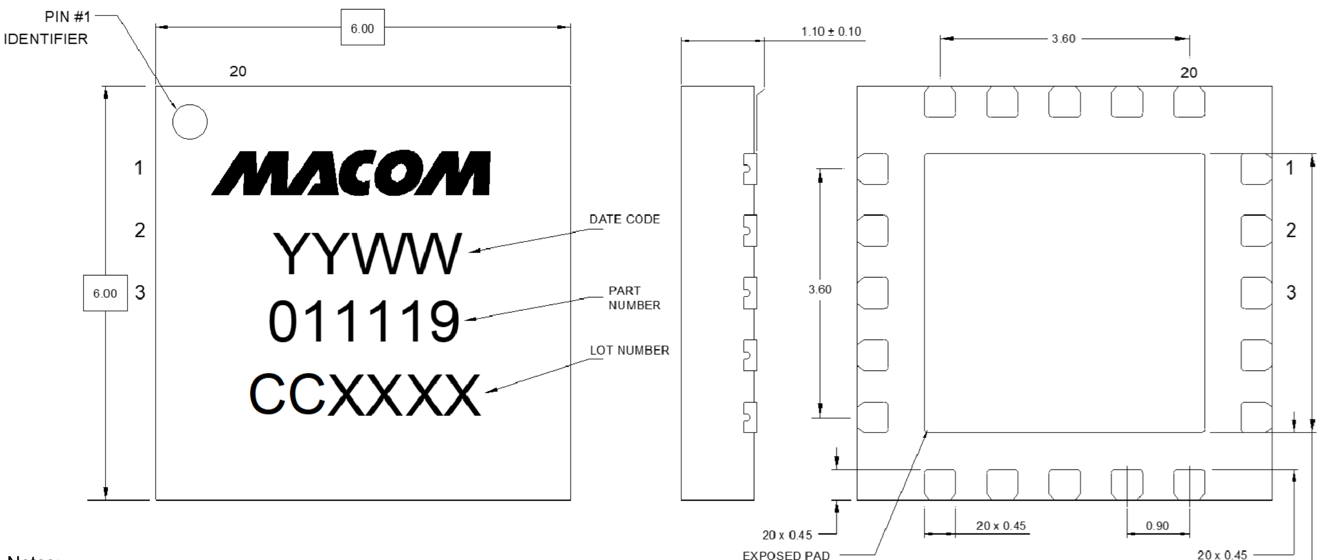
Part	Value	Case style
C1	10 µF	0603
C2	5 pF	0402
C3	10 nF	0402
C4	470 pF	0402
R1	1 kΩ	0402
R2	100 Ω	0402

Recommended Thermal Land Pattern



- 25 Ground Vias
- 0.5 mm Diameter, 1/2 oz. Copper

Lead-Free 6 mm 20-Lead QFN†



Notes:
1. All dimensions shown in mm.
2. Reference JEDEC MO-220 for additional dimensional and tolerance information.

† Reference Application Note S2083 for lead-free solder reflow recommendations.
Meets JEDEC moisture sensitivity level 3 requirements in accordance to JEDEC J-STD-020D.
Plating is NiPdAuAg over Copper